

Datasheet revision 1.2

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Solder Wire Sn96.5/Ag3.5 No-Clean with 2.0% Flux Core 0.5oz Tube

Product Highlights No-Clean Synthetic Flux Core The clear, non-corrosive, non-conductive residue is meant to be left on the board. 2.0% flux core Halogen content: None RoHS 3 and REACH compliant

Specifications

Alloy: Wire Diameter: Flux Type: Flux Classification: Melting Point: Packaging: Shelf Life: Sn96.5/Ag3.5 0.031" (0.8mm) No-Clean Synthetic ROL0 221°C (430°F) 0.5oz Tube >60 months



Test Results

Test J-STD-004 or other requirements as stated	Test Requirement	Result
Copper Mirror	IPC-TM-650: 2.3.32	L: No breakthrough
Corrosion	IPC-TM-650: 2.6.15	L: No corrosion
Quantitative Halides	IPC-TM-650: 2.3.28.1	L: <0.05%
Electrochemical Migration	IPC-TM-650: 2.6.14.1	L: <1 decade drop (No-clean)
Surface Insulation Resistance 85°C, 85% RH @ 168 Hours	IPC-TM-650: 2.6.3.7	L: ≥100MΩ (No-clean)
Visual	IPC-TM-650: 3.4.2.5	Clear and free from precipitation
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials

Conforms to the following Industry Standards:J-STD-004B, Amendment 1 (Solder Fluxes):YesJ-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders):YesRoHS 3 Directive (EU) 2015/863:Yes